# Hex D Flip-Flop with Common Clock and Reset

This device consists of six D flip-flops with common Clock and Reset inputs. Each flip-flop is loaded with a low-to-high transition of the Clock input. Reset is asynchronous and active low. All inputs/outputs are standard CMOS compatible.

#### **Features**

• Output Drive Compatibility: 10 LSTTL Loads

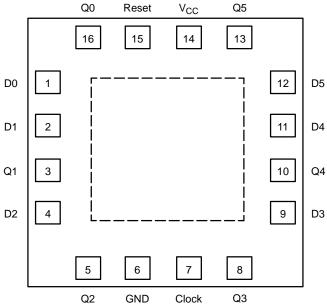
• Outputs Directly Interface to CMOS

• Operating Voltage Range: 2 to 6 V

• Low Input Current: 1.0 μA

• MSL Level 1

• Chip Complexity: 162 FET



Center pad on bottom may be connected to  $V_{CC}$  of device. This pad must be isolated or connected to  $V_{CC}$ .

Figure 1. Pin Assignment (Top View)

#### **FUNCTION TABLE**

	Output		
Reset	Clock	D	Q
L	Х	Х	L
Н	_	Н	Н
Н	_	L	L
Н	L	Х	No Change
Н	~	Х	No Change

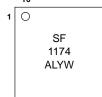


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MARKING DIAGRAM



QFN-16 MN SUFFIX CASE 485G



A = Assembly Location

L = Wafer Lot Y = Year W = Work Week

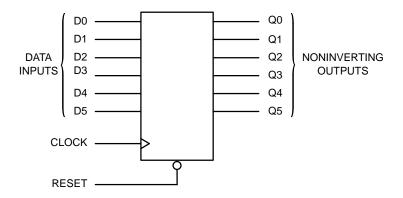


Figure 2. Logic Diagram

# **DESIGN/VALUE TABLE**

Design Criteria	Value	Units
Internal Gate Count*	40.5	ea.
Internal Gate Propagation Delay	1.5	ns
Internal Gate Power Dissipation	5.0	μW
Speed Power Product	.0075	рJ

<sup>\*</sup>Equivalent to a two-input NAND gate.

#### **MAXIMUM RATINGS** (Note 1)

Symbol	Pi	arameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	(Referenced to GND)	-0.5  to  +7.0	V
V <sub>IN</sub>	DC Input Voltage	(Referenced to GND)	-1.5 to V <sub>CC</sub> +1.5	V
V <sub>OUT</sub>	DC Output Voltage	(Referenced to GND) (Note 2)	$-0.5$ to $V_{CC} + 0.5$	V
I <sub>IN</sub>	DC Input Current, per Pin		±20	mA
l <sub>OUT</sub>	DC Output Current, per Pin		±25	mA
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pir	ns	±50	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for	or 10 Seconds PDIP, SOIC, TSSOP	260	°C
TJ	Junction Temperature Under Bias		+150	°C
$\theta_{JA}$	Thermal Resistance	QFN	80	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C	QFN	800	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 30 to 35	UL 94 V-O @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	>2000 >100 >500	V
I <sub>LATCH</sub> - UP	Latch-Up Performance	Above V <sub>CC</sub> and Below GND at 85°C (Note 6)	±300	mA

<sup>1.</sup> Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Extended exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum-rated conditions is not implied.

- I<sub>O</sub> absolute maximum rating must be observed.
   Tested to EIA/JESD22-A114-A.
- 4. Tested to EIA/JESD22-A115-A.
- 5. Tested to JESD22-C101-A.
- 6. Tested to EIA/JESD78.
- 7. For high frequency or heavy load considerations, see the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

# **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	DC Supply Voltage	(Referenced to GND)	2.0	6.0	V
V <sub>IN</sub> , V <sub>OUT</sub>	DC Input Voltage, Output Voltage	(Referenced to GND) (Note 8)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature, All Package Types		- 55	+ 125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Figure 4)	V <sub>CC</sub> = 2.0 V V <sub>CC</sub> = 4.5 V V <sub>CC</sub> = 6.0 V	0 0 0	1000 500 400	ns

8. Unused inputs may not be left open. All inputs must be tied to a high- or low-logic input voltage level.

# DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

			V <sub>CC</sub>	Guaran	teed Limi	t	
Symbol	Parameter	Test Conditions	V	-55°C to 25°C	≤ <b>85°C</b>	≤125°C	Unit
V <sub>IH</sub>	Minimum High-Level Input Voltage	$V_{OUT}$ = 0.1 V or $V_{CC}$ – 0.1 V $ I_{OUT}  \le 20 \mu A$	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V <sub>IL</sub>	Maximum Low-Level Input Voltage	$V_{OUT}$ = 0.1 V or $V_{CC}$ – 0.1 V $ I_{OUT}  \le 20 \mu A$	2.0 4.5 6.0	0.5 1.35 1.8	0.5 1.35 1.8	0.5 1.35 1.8	V
V <sub>OH</sub>	Minimum High-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 20 \ \mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 4.0 \text{ mA}$ $ I_{OUT}  \le 5.2 \text{ mA}$	4.5 6.0	3.98 5.48	3.84 5.34	3.7 5.2	
V <sub>OL</sub>	Maximum Low-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 20 \ \mu\text{A}$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 4.0 \text{ mA}$ $ I_{OUT}  \le 5.2 \text{ mA}$	4.5 6.0	0.26 0.26	0.33 0.33	0.4 0.4	
I <sub>IN</sub>	Maximum Input Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	6.0	± 0.1	±1.0	±1.0	μΑ
Icc	Maximum Quiescent Supply Current (per Package)	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0	4.0	40	160	μΑ

Information on typical parametric values, along with high frequency or heavy load considerations, can be found in the ON Semiconductor High- Speed CMOS Data Book (DL129/D).

# AC ELECTRICAL CHARACTERISTICS ( $C_L = 50 \text{ pF}$ , Input $t_f = t_f = 6.0 \text{ ns}$ )

Symbol	Parameter	V <sub>CC</sub>	Guaran	Unit		
		V	-55°C to 25°C	≤ <b>85°C</b>	≤125°C	
f <sub>max</sub>	Maximum Clock Frequency (50% Duty Cycle) (Figures 4 and 7)	2.0 4.5 6.0	6.0 30 35	4.8 24 28	4.0 20 24	MHz
t <sub>PLH</sub> t <sub>PHL</sub>	Maximum Propagation Delay, Clock to Q (Figures 5 and 7)	2.0 4.5 6.0	110 22 19	140 28 24	165 33 28	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Maximum Propagation Delay, Reset to Q (Figures 2 and 7)	2.0 4.5 6.0	110 21 19	140 28 24	160 32 27	ns
t <sub>TLH</sub> t <sub>THL</sub>	Maximum Output Transition Time, Any Output (Figures 4 and 7)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C <sub>in</sub>	Maximum Input Capacitance		10	10	10	pF

<sup>10.</sup> For propagation delays with loads other than 50 pF, and information on typical parametric values, see the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

			Typical @ 25°C, V <sub>CC</sub> = 5.0 V		
$C_{PD}$	Power Dissipation Capacitance, per Enabled Output	(Note 11)	62	рF	

<sup>11.</sup> Used to determine the no-load dynamic power consumption:  $P_D = C_{PD} \ V_{CC}^2 f + I_{CC} \ V_{CC}$ . For load considerations, see the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

TIMING REQUIREMENTS ( $C_L = 50 \text{ pF}$ , Input  $t_f = t_f = 6.0 \text{ ns}$ )

				Guaranteed Limit						
			V <sub>CC</sub>	−55°C	to 25°C	≤8	5°C	≤12	25°C	
Symbol	Parameter	Figure	V	Min	Max	Min	Max	Min	Max	Unit
t <sub>su</sub>	Minimum Setup Time, Data to Clock	6	2.0 4.5 6.0	50 10 9.0		65 13 11		75 15 13		ns
t <sub>h</sub>	Minimum Hold Time, Clock to Data	6	2.0 4.5 6.0	5.0 5.0 5.0		5.0 5.0 5.0		5.0 5.0 5.0		ns
t <sub>rec</sub>	Minimum Recovery Time, Reset Inactive to Clock	5	2.0 4.5 6.0	5.0 5.0 5.0		5.0 5.0 5.0		5.0 5.0 5.0		ns
t <sub>w</sub>	Minimum Pulse Width, Clock	4	2.0 4.5 6.0	75 15 13		95 19 16		110 22 19		ns
t <sub>w</sub>	Minimum Pulse Width, Reset	5	2.0 4.5 6.0	75 15 13		95 19 16		110 22 19		ns
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Times	4	2.0 4.5 6.0		1000 500 400		1000 500 400		1000 500 400	ns

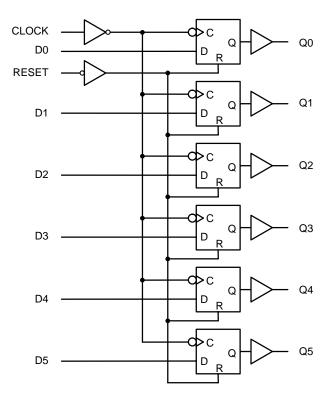


Figure 3. Expanded Logic Diagram

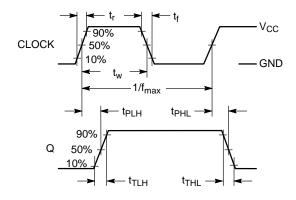


Figure 4. Switching Waveform

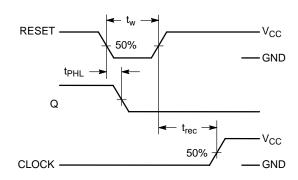


Figure 5. Switching Waveform

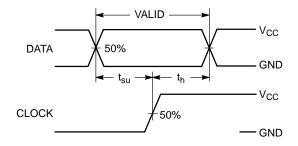
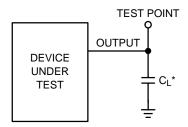


Figure 6. Switching Waveform



\*Includes all probe and jig capacitance

Figure 7. Test Circuit

# **DEVICE ORDERING INFORMATION**

		Dev	ice Nomencla	ture			
Device Order Number	Circuit Indicator	Technology	Device Function	Package Suffix	Tape & Reel Suffix	Package Type	Tape & Reel Size
NLSF1174MNR2	NL	SF	1174	MN	R2	QFN	7-inch/2500 Unit

# PIN1/PRODUCT ORIENTATION CARRIER TAPE

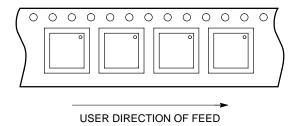
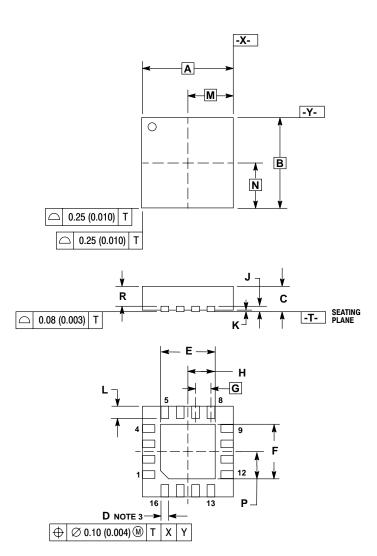


Figure 8.

# **PACKAGE DIMENSIONS**

## **QFN-16 MN SUFFIX** CASE 485G-01 ISSUE A



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION D APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
  4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	3.00	BSC	0.118	BSC	
В	3.00	BSC	0.118	BSC	
С	0.80	1.00	0.031	0.039	
D	0.23	0.28	0.009	0.011	
Е	1.75	1.85	0.069	0.073	
F	1.75	1.85	0.069	0.073	
G	0.50	BSC	0.020 BSC		
Н	0.875	0.925	0.034	0.036	
J	0.20 REF		0.008	REF	
K	0.00	0.05	0.000	0.002	
L	0.35	0.45	0.014	0.018	
M	1.50	1.50 BSC		BSC	
N	1.50	BSC	0.059	BSC	
P	0.875	0.925	0.034	0.036	
R	0.60	0.80	0.024	0.031	

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